

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

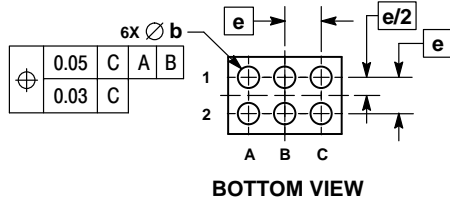
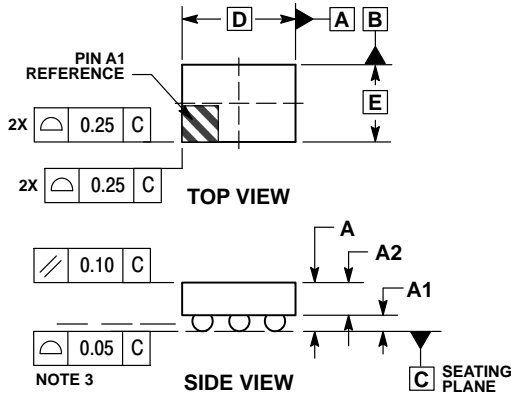
ON Semiconductor®



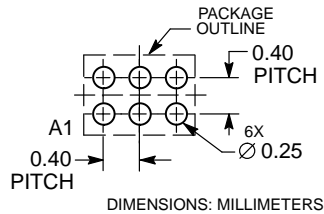
SCALE 4:1

WLCSP6, 1.25x0.85  
CASE 567GZ  
ISSUE B

DATE 02 DEC 2014



### RECOMMENDED SOLDERING FOOTPRINT\*

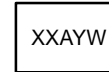


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.62
A1	0.17	0.23
A2	0.36	REF
b	0.24	0.29
D	1.25	BSC
E	0.85	BSC
e	0.40	BSC

### GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- Y = Year
- W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP6, 1.25X0.85	PAGE 1 OF 2

